

ABSTRACT

A circuit board having high adhesiveness contact between electrically insulating layers and having a low interlayer electric resistance is provided. A circuit board is provided with a first conductive layer formed on a core (1) and a first electrically insulating layer formed thereon. In the circuit board, a first conductor layer has a surface roughness Ra of 0.1nm or more but less than 100nm, and a first primer layer having a thiol compound as a main material is provided between the first conductive layer and the first electrically insulating layer. Thus, the circuit board which has excellent adhesiveness between the first conductor layer and the first electrically insulating layer and is also applicable to high frequency signal is provided.